onsemi

TinyLogic UHS D-Type, Flip-Flop with Preset and Clear

NC7SZ74

Description

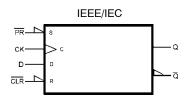
The NC7SZ74 is a single, D-type, CMOS flip-flop with preset and clear from **onsemi** ultra high-speed series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive, while maintaining low static power dissipation over a very broad V_{CC} operating range of 1.65 V to 5.5 V V_{CC} . The inputs and outputs are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 5.5 V, independent of V_{CC} operating voltage.

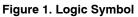
The signal level applied to the D input is transferred to the Q output during the positive–going transition of the CLK pulse.

Features

- Ultra-High Speed: t_{PD} 2.6 ns (Typical) into 50 pF at 5 V V_{CC}
- High Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Power Down High-Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise/EMI Reduction Circuitry

CONNECTION DIAGRAM



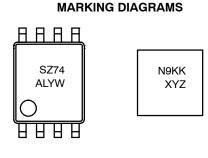






US8 CASE 846AN

UQFN8 1.6X1.6, 0.5P CASE 523AY



SZ74, N9	= Specific Device Code
Α	– Assembly Site

= Assembly Site = Wafer Lot Number

L

YW

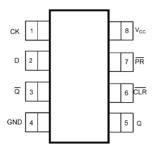
KK

XY

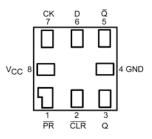
Ζ

- = Assembly Start Wee
- = 2-Digit Lot Run Traceability Code
- = 2-Digit Date Code Format
 - = Assembly Plant Code

PIN CONFIGURATIONS



USB (Top View)



MicroPak[™] (Top Through View)

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

PIN DEFINITIONS

Pin # US8	Pin # MicroPak	Name	Description
1	7	СК	Clock Pulse Input
2	6	D	Data Input
3	5	Q	Flip–Flop Output
4	4	GND	Ground
5	3	Q	Flip–Flop Output
6	2	CLR	Direct Clear Input
7	1	PR	Direct Preset Input
8	8	Vcc	Supply Voltage

FUNCTION TABLE

	Inputs Output					
CLR	PR	D	СК	Q	Q	Function
L	Н	Х	Х	L	Н	Clear
Н	L	Х	Х	Н	L	Preset
L	L	Х	Х	Н	н	
Н	Н	L	\uparrow	L	н	
Н	Н	Н	\uparrow	Н	L	
Н	Н	Х	\downarrow	Q _n	\overline{Q}_{n}	No Change
H	= HIGH Logic Leve	el Qn = N	lo change in data	X = Immateria	al \downarrow = Falling Edge	9

L

Z = High Impedance

 \uparrow = Rising Edge

ABSOLUTE MAXIMUM RATINGS

Symbol	Param	Min	Max	Unit	
V _{CC}	Supply Voltage		-0.5	6.5	V
V _{IN}	DC Input Voltage		-0.5	6.5	V
V _{OUT}	DC Output Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	-	-50	mA
Ι _{ΟΚ}	DC Output Diode Current	V _{OUT} < 0 V	-	-50	mA
I _{OUT}	DC Output Source/Sink Current	•	-	±50	mA
I_{CC} or I_{GND}	DC V _{CC} or Ground Current		-	±50	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under Bias		-	+150	°C
TL	Junction Lead Temperature (Soldering,	10 Seconds)	-	+260	°C
P _D	Power Dissipation in Still Air	-	500 539	mW	
ESD	Human Body Model: JEDEC:JESD22-,	-	4000	V	
	Charge Device Model: JEDEC:JESD22	2-C101	-	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.50	V
	Supply Voltage Data Retention		1.50	5.50	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT} Output Voltag	Output Voltage	Active State	0	Vcc	V
		3-State	0	5.5	
t _r , t _f	Input Rise and Fall Times	V_{CC} = 1.8 V, 2.5 V ±0.2 V	0	20	ns/V
		$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0	10	
		$V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0	5	
T _A	Operating Temperature		-40	+85	°C
θ_{JA}	Thermal Resistance	US8		250	°C/W
		MicroPak-8		232	7

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

NOTE: Unused inputs must be held HIGH or LOW. They may not float.

DC ELECTRICAL CHARACTERISTICS

				Τ ₄	_ = +25°	°C	T _A = -40	to +85°C	
Symbol	Parameter	Vcc	Conditions	Min	Тур	Max	Min	Max	Units
V _{IH}	HIGH Level Control	1.65 to 1.95		0.65 V _{CC}			0.65 V _{CC}		V
	Input Voltage	2.30 to 5.50		0.70 V _{CC}			0.70 V _{CC}		
V _{IL}	LOW Level Control	1.65 to 1.95				0.35 V _{CC}		0.35 V _{CC}	V
	Input Voltage	2.30 to 5.50				0.30 V _{CC}		0.30 V _{CC}	
V _{OH}	HIGH Level Output	1.65	VIN = VIH,	1.55	1.65		1.55		V
	Voltage	2.30	I _{OH} = −100 μA	2.20	2.30		2.20		
		3.00		2.90	3.00		2.90		
		4.50		4.40	4.50		4.40		
		1.65	I _{OH} = -4 mA	1.29	1.52		1.29		
		2.30	I _{OH} = -8 mA	1.90	2.15		1.90		
		3.00	I _{OH} = -16 mA	2.40	2.80		2.40		
		3.00	I _{OH} = -24 mA	2.30	2.68		2.30		
		4.50	I _{OH} = -32 mA	3.80	4.20		3.80		
V _{OL}	LOW Level Control	1.65	$V_{IN} = V_{IH},$			0.10		0.10	V
	Output Voltage	2.30	I _{OL} = 100 μA			0.10		0.10	
		3.00				0.10		0.10	
		4.50				0.10		0.10	
		1.65	I _{OL} = 4 mA		0.10	0.24		0.24	
		2.30	I _{OL} = 8 mA		0.10	0.30		0.30	
		3.00	I _{OL} = 16 mA		0.15	0.40		0.40	
		3.00	I _{OL} = 24 mA		0.22	0.55		0.55	
		4.50	I _{OL} = 32 mA		0.22	0.55		0.55	
I _{IN}	Input Leakage Current	1.65 to 5.5	$0 \le V_{IN} \le 5.5 \text{ V}$			±0.1		±1.0	μΑ
I _{OFF}	Power Off Leakage Current	0	V_{IN} or V_{OUT} = 5.5 V			1		10	μΑ
I _{CC}	Quiescent Supply Current	1.65 to 5.50	V _{IN} = 5.5 V, GND			1		10	μΑ

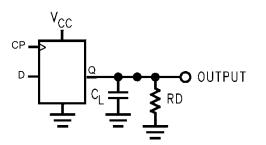
AC ELECTRICAL CHARACTERISTICS

				$T_A = +25^{\circ}C$ $T_A = -40 \text{ to } +85^{\circ}C$) to +85°C						
Symbol	Parameter	V _{CC}	Conditions	Min	Тур	Max	Min	Max	Units	Figure	
f _{MAX}	Maximum Clock	1.80 ±0.15	$C_L = 15 \text{ pF},$	75			75		MHz	Figure 4	
	Frequency	2.50 ±0.20	R _D = 1 MΩ, S ₁ = Open	150			150			Figure 8	
		3.30 ±0.30]	200			200				
		5.00 ± 0.50		250			250				
		3.30 ± 0.50	C _L = 50 pF, R _D = 500 Ω,	175			175				
		5.00 ±0.50	S ₁ = Open	200			200				
t _{PLH} , t _{PHL}	Propagation Delay	1.80 ±0.15	C _L = 15 pF,		6.5	12.5		13.0	ns	Figure 4	
	CK to Q, \overline{Q}	2.50 ±0.20	$R_D = 1 M\Omega,$ S ₁ = Open		3.8	7.5		8.0		Figure 6	
		3.30 ±0.30			2.8	6.5		7.0			
		5.00 ± 0.50			2.2	4.5		5.0			
		3.30 ±0.30	$C_{L} = 50 \text{ pF},$		3.4	7.0		7.5			
		5.00 ±0.50	- R _D = 500 Ω, S ₁ = Open		2.6	5.0		5.5	1		
t _{PLH} , t _{PHL}	Propagation Delay	1.80 ±0.15	C _L = 15 pF,		6.5	14.0		14.5	ns	ns	Figure 4
	$\overline{\text{CLR}}$, $\overline{\text{PR}}$ to Q, $\overline{\text{Q}}$	2.50 ±0.20	R _L = 1 ΜΩ, S ₁ = Open		3.8	9.0		9.5		Figure 6	
		3.30 ±0.30			2.8	6.5		7.0			
		5.00 ±0.50			2.2	5.0		5.5			
		3.30 ±0.30	$C_{L} = 50 \text{ pF},$		3.4	7.0		7.5	$\frac{1}{2}$		
		5.00 ±0.50	- R _D = 500 Ω, S ₁ = Open		2.6	5.0		5.5			
t _S	Setup Time CK to D	1.80 ±0.15	C _L = 15 pF,	6.5			6.5		ns	Figure 4	
		2.50 ±0.20	$R_L^- = 1 M\Omega,$ S ₁ = Open	3.5			3.5		-	Figure 7	
		3.30 ±0.30		2.0			2.0				
		5.00 ±0.50		1.5			1.5				
		3.30 ±0.30	$C_{L} = 50 \text{ pF},$	2.0			2.0		1		
		5.00 ±0.50	- R _D = 500 Ω, S ₁ = Open	1.5			1.5		1		
t _H	Hold Time, CK to D	1.80 ±0.15	C _L = 15 pF,	0.5			0.5		ns	Figure 4	
		2.50 ±0.20	R _L = 1 MΩ, S ₁ = Open	0.5			0.5		1	Figure 7	
		3.30 ±0.30		0.5			0.5		1		
		5.00 ±0.50		0.5			0.5				
		3.30 ±0.30	$C_{L} = 50 \text{ pF},$	0.5			0.5				
		5.00 ±0.50	- R _D = 500 Ω, S ₁ = Open	0.5			0.5		1		
t _W	Pulse Width, CK,	1.80 ±0.15	C _L = 15 pF,	6.0			6.0		ns	Figure 4	
	PR, CLR	2.50 ±0.20	$R_L = 1 M\Omega,$ $S_1 = Open$	4.0			4.0		1	Figure 8	
		3.30 ±0.30		3.0			3.0		1		
		5.00 ±0.50	-	2.0			2.0		1		
		3.30 ±0.30	C _L = 50 pF,	3.0			3.0		1		
		5.00 ±0.50	- R _D = 500 Ω, S ₁ = Open	2.0			2.0		1		
t _{REC}	Recover Time CLR,	1.80 ±0.15	C _L = 15 pF,	8.0			8.0		ns	Figure 7	
	PR to CK	2.50 ±0.20	$R_{L}^{-} = 1 M\Omega,$ $S_{1} = Open$	4.5			4.5		1		
		3.30 ±0.30		3.0			3.0		1		
		5.00 ±0.50	1	3.0	1		3.0		1		
		3.30 ±0.30	C _L = 50 pF,	3.0			3.0		——		
		5.00 ±0.50	- R _D = 500 Ω, S ₁ = Open	3.0		1	3.0		1		

				T,	A = +25°0	0	T _A = -40	to +85°C		
Symbol	Parameter	V _{CC}	Conditions	Min	Тур	Max	Min	Max	Units	Figure
C _{IN}	Input Capacitance	0			3				pF	
C _{OUT}	Output Capacitance	0			4				pF	
C _{PD}	Power Dissipation	3.30			10				pF	
	Capacitance (Note 1)	5.00			12					

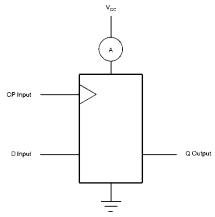
AC ELECTRICAL CHARACTERISTICS (continued)

1. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. CPD is related to ICCD dynamic operating current by the expression: $I_{CCD} = (C_{PD})(V_{CC})(f_{IN}) + (I_{CC}static).$



2. CL includes load and stray capacitance. Input PRR = 1.0 MHz $t_{\rm w}$ = 500 ns.





- 3. CP input = AC Waveforms $t_r = t_f = 2.5$ ns.
- CP input PRR = 10 MHz; Duty Cycle = 50%.
 D input PRR = 5 MHz; Duty Cycle = 50%.

Figure 3. AC Test Circuit

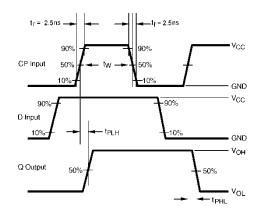


Figure 4. AC Waveforms

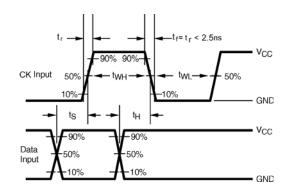


Figure 5. AC Waveforms

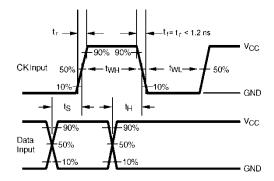


Figure 6. AC Waveforms

NC7SZ74

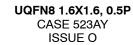
ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method [†]		
NC7SZ74K8X	SZ74	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide	3000 Units on Tape & Reel		
NC7SZ74K8X-L22236	SZ74	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide	3000 Units on Tape & Reel		
NC7SZ74L8X	N9	8-Lead MicroPak, 1.6 mm Wide	5000 Units on Tape & Reel		
NC7SZ74L8X-L22185	N9	8-Lead MicroPak, 1.6 mm Wide	5000 Units on Tape & Reel		

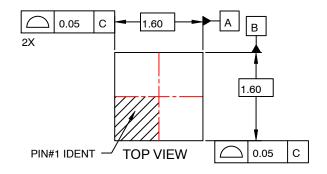
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

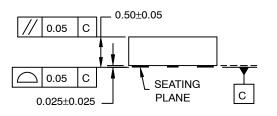
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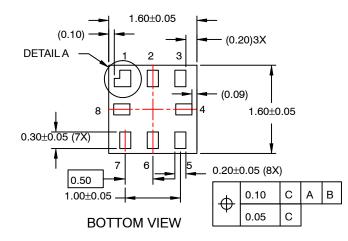


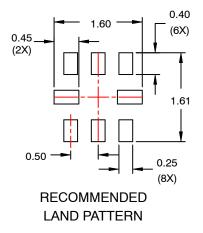
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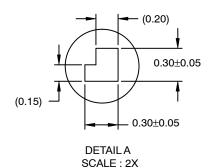
SIDE VIEW





NOTES:

- A. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.



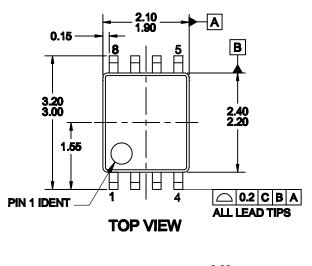
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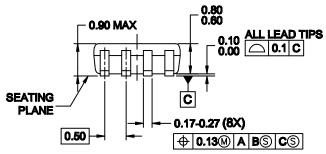
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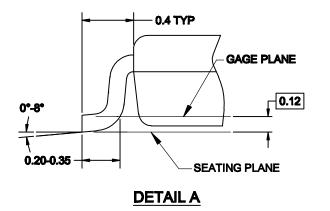
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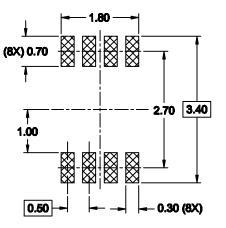
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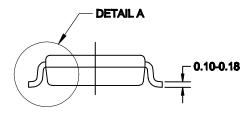




RECOMMENDED LAND PATTERN

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-187
- **B. DIMENSIONS ARE IN MILLIMETERS.**
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- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1994.



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